



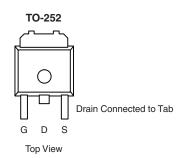
P-Channel 60-V (D-S), 175 °C MOSFET, Logic Level

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)		
- 60	0.170 at V _{GS} = - 10 V	- 10		
	0.280 at V _{GS} = - 4.5 V	- 8		

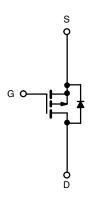
FEATURES

- TrenchFET® Power MOSFETs
- 175 °C Rated Maximum Junction Temperature





Ordering Information: SUD10P06-280L-E3 (Lead (Pb)-free)



P-Channel MOSFET

ABSOLUTE MAXIMUM RATING			1114		
Parameter		Symbol	Limit	Unit	
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C	1_	- 10		
	T _C = 100 °C	- 'D -	- 7		
Pulsed Drain Current		I _{DM}	- 20	Α	
Continuous Source Current (Diode Conduction)		I _S	- 10		
Avalanche Current		I _{AS}	- 10		
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	5	mJ	
Maximum Bower Discinction	T _C = 25 °C	PD	37	W	
Maximum Power Dissipation	T _A = 25 °C] '	2 ^a		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Junction-to-Ambient ^a	FR4 Board Mount	R _{thJA}	60	70	°C/W	
	Free Air		120	140		
Junction-to-Case	·	R _{thJC}	3.7	4.0		

Notes:

a. Surface Mounted on FR4 board.

For SPICE model information via the Worldwide Web: http://www.vishay.com/www/product/spice.htm.

SUD10P06-280L

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Parameter	Symbol	Test Conditions		Typ. ^a	Max.	Unit	
Static	,						
Drain-Source Breakdown Voltage	V _{DS}	V_{DS} $V_{DS} = 0 \text{ V, } I_{D} = -250 \mu\text{A}$ - 60				.,	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0	- 2.0	- 3.0	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current		V _{DS} = - 60 V, V _{GS} = 0 V			- 1		
	I _{DSS}	V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 125 °C			- 50	μΑ	
		V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 175 °C			- 150		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 10			Α	
Drain-Source On-State Resistance ^b		V _{GS} = - 10 V, I _D = - 5 A		0.130	0.170	Ω	
	D	V _{GS} = - 10 V, I _D = - 5 A, T _J = 125 °C			0.31		
	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 5 A, T _J = 175 °C			0.375		
		V _{GS} = - 4.5 V, I _D = - 2 A		0.210	0.280		
Forward Transconductance ^b	9 _{fs}	V _{DS} = - 15 V, I _D = - 5 A		6		S	
Dynamic	•						
Input Capacitance	C _{iss}			635		pF	
Output Capacitance	C _{oss}	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		100			
Reverse Transfer Capacitance	C _{rss}			30			
Total Gate Charge	Q_g			11.5	25		
Gate-Source Charge	Q_{gs}	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -10 \text{ A}$		3.5		nC	
Gate-Drain Charge	Q_{gd}			2			
Turn-On Delay Time ^c	t _{d(on)}			9	20		
Rise Time ^c	t _r	V_{DD} = - 30 V, R_L = 3 Ω		16	20	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = -10 \text{ V}, R_G = 2.5 \Omega$		17	30		
Fall Time ^c	t _f	j		19	35		
Source-Drain Diode Ratings and Cha	aracteristics	$T_C = 25 ^{\circ}C^a$			<u> </u>		
Pulsed Current	I _{SM}				- 20	Α	
Forward Voltage ^b	V_{SD}	I _F = 10 A, V _{GS} = 0 V			- 1.3	V	
Reverse Recovery Time	t _{rr}	I _F = 10 A, dl/dt = 100 A/μs		50	80	ns	

Notes:

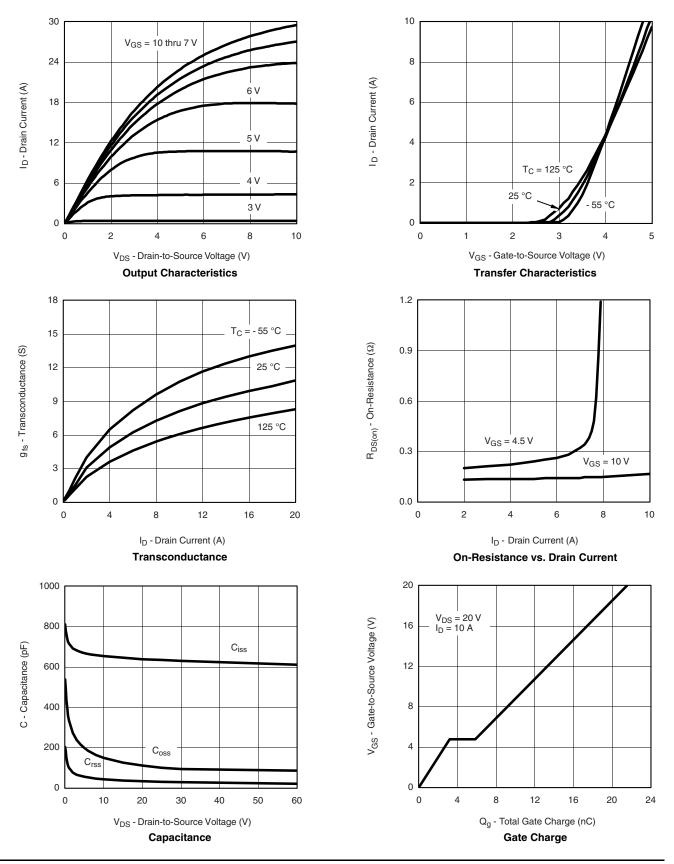
- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



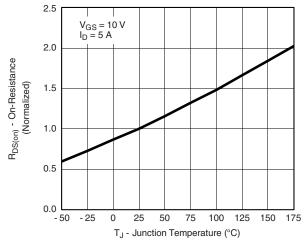


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

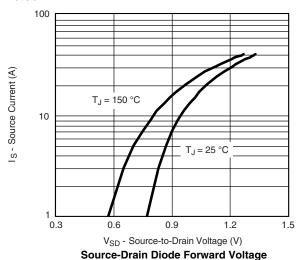


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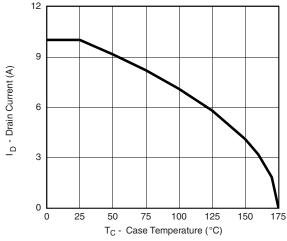
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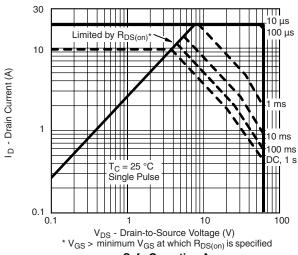
On-Resistance vs. Junction Temperature



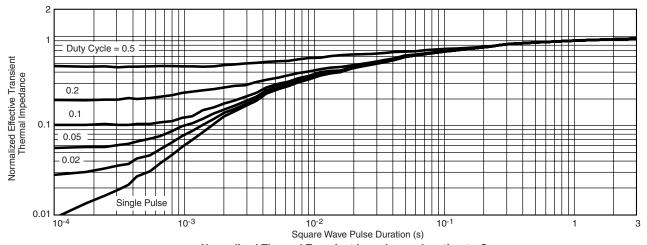
THERMAL RATINGS



Drain Current vs. Case Temperature







Normalized Thermal Transient Impedance, Junction-to-Case

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